



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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TECHNOLOGY CENTER 2800

Applicant: Paul A. Farrar  
Title: INSULATORS FOR HIGH DENSITY CIRCUITS

Docket No.: 303.610US1  
Filed: August 25, 1999  
Examiner: Fetsum Abraham

Serial No.: 09/382,524  
Due Date: November 13, 2002  
Group Art Unit: 2826

Commissioner for Patents  
Washington, D.C. 20231

We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ A return postcard.
- ☒ An Amendment and Response (8 Pages).
- ☒ A Clean Version of Pending Claims (5 pgs.).
- ☒ A check in the amount of \$594.00 to cover the fee for additional claims as calculated below.

If an additional fee is required due to changes to the claims, the fee has been calculated as follows:

CLAIMS AS AMENDED						
	(1) Claims Remaining After Amendment		(2) Highest Number Previously Paid For	(3) Present Extra	Rate	Fee
TOTAL CLAIMS	25	-	20	5	x 18 =	\$90.00
INDEPENDENT CLAIMS	10	-	4	6	x 84 =	\$504.00
[ ] MULTIPLE DEPENDENT CLAIMS PRESENTED						\$0.00
TOTAL						\$594.00

Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

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By:   
Atty: Danny J. Padys  
Reg. No. 35,635

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on this 13 day of November, 2002.

Name

Signature

Customer Number 21186

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
(GENERAL)

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S/N 09/382,524

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PATENT

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fee OK

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TECHNOLOGY CENTER 2800AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111Commissioner for Patents  
Washington, D.C. 20231

Applicant has reviewed the office action mailed on August 13, 2002. Please amend the above-identified patent application as follows.

IN THE CLAIMS

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect amendment of previously pending claims 1-3, 5-7, 10-11, and 42-43 and addition of new claims 46-57. The specific amendments to individual claims are detailed in the following marked up set of claims.

1. (Amended) [An] A conductive system comprising:  
a substrate;  
a foamed material layer on the substrate, the foamed material layer having a surface that is hydrophobic; and  
a plurality of conductive structures embedded in the foamed material layer.
2. (Amended) A conductive system comprising:  
a substrate;  
a foamed material layer on the substrate, the foamed material layer having a surface that is hydrophobic; and  
a plurality of conductive structures embedded in the foamed material layer. [The conductive system of claim 1,] wherein the foamed material layer has a foamed thickness of between about .4 microns and about 3.4 microns.

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